

SL-SMT 3.50/16/180F 3.2SN BK BX SO

Weidmüller Interface GmbH & Co. KG
 Klingenbergstraße 26
 D-32758 Detmold
 Germany

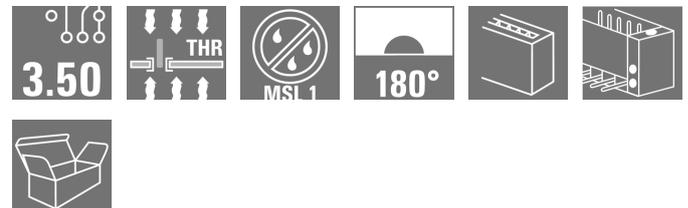
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Product image


Similar to illustration

High-temperature-resistant male header, 3.50 mm pitch.

- **Plugging direction parallel (90°), straight 180° or angled (135°) to PCB**
- **Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)**
- **Optimised for the SMT process**
- **Pin length 3.2 mm universal for all soldering methods**
- **Pin length 1.5 mm optimised for reflow soldering methods**
- **Packed either in a box (BX) or tape-on-reel (RL)**
- **Male header can be coded**


General ordering data

Version	PCB plug-in connector, male header, Flange, THT/THR solder connection, 3.50 mm, Number of poles: 16, 180°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	2535480000
Type	SL-SMT 3.50/16/180F 3.2SN BK BX SO
GTIN (EAN)	4050118547221
Qty.	24 pc(s).
Product data	IEC: 320 V / 15 A UL: 300 V / 10 A
Packaging	Box

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Technical data
Dimensions and weights

Net weight	5.48 g	Width	63 mm
Width (inches)	2.48 inch		

System specifications

Product family	OMNIMATE Signal - series BL/SL 3.50		
Type of connection	Board connection		
Mounting onto the PCB	THT/THR solder connection		
Pitch in mm (P)	3.5 mm		
Pitch in inches (P)	0.138 inch		
Outgoing elbow	180°		
Number of poles	16		
Number of solder pins per pole	1		
Solder pin length (l)	3.2 mm		
Solder pin length tolerance	0 / -0.3 mm		
Solder pin dimensions	d = 1.2 mm, Octagonal		
Solder pin dimensions = d tolerance	0 / -0.03 mm		
Solder eyelet hole diameter (D)	1.4 mm		
Solder eyelet hole diameter tolerance (D)	+ 0,1 mm		
Outside diameter of solder pad	2.3 mm		
Template aperture diameter	2.1 mm		
L1 in mm	52.5 mm		
L1 in inches	2.067 inch		
Number of rows	1		
Pin series quantity	1		
Touch-safe protection acc. to DIN VDE 57 106	Safe from back-of-hand touch		
Touch-safe protection acc. to DIN VDE 0470	IP 10		
Volume resistance	≤5 mΩ		
Can be coded	Yes		
Plugging cycles	25		
Plugging force/pole, max.	6 N		
Pulling force/pole, max.	6 N		
Tightening torque	Torque type	Mounting screw, PCB	
	Usage information	Tightening torque	min. 0.1 Nm max. 0.15 Nm
		Recommended screw	Part number PTSC KA 2.2X4.5 WN1412

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact material	CuSn	Contact surface	tinned
Layer structure of solder connection	2...3 μm Ni / 5...7 μm Sn	Layer structure of plug contact	2...3 μm Ni / 5...7 μm Sn
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	100 °C
Temperature range, installation, min.	-30 °C	Temperature range, installation, max.	100 °C

Creation date April 16, 2021 12:01:33 AM CEST

Catalogue status 09.04.2021 / We reserve the right to make technical changes.

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Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	15 A
Rated current, max. number of poles (Tu=20°C)	12 A	Rated current, min. number of poles (Tu=40°C)	13 A
Rated current, max. number of poles (Tu=40°C)	10 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 100 A

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	10 A	Rated current (Use group D / CSA)	10 A

Rated data acc. to UL 1059

Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	10 A	Rated current (Use group D / UL 1059)	10 A

Packing

Packaging	Box	VPE length	338 mm
VPE width	130 mm	VPE height	14 mm

Important note

IPC conformity Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

- Notes
- Gold-plated contact surfaces on request
 - Rated current related to rated cross-section & min. No. of poles.
 - Diameter of solder eyelet D = 1.4+0.1mm
 - Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles
 - P on drawing = pitch
 - Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
 - For additional mechanical support for male connectors with screw flange (...F), we recommend an additional cable gland with fastening screws (sheet metal screw ISO 1481-ST 2.2x4.5 C or ISO 7049-ST 2.2x4.5 C - see Accessories). Cable gland only permitted before soldering.
 - Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Downloads

Brochure/Catalogue [Catalogues in PDF-format](#)

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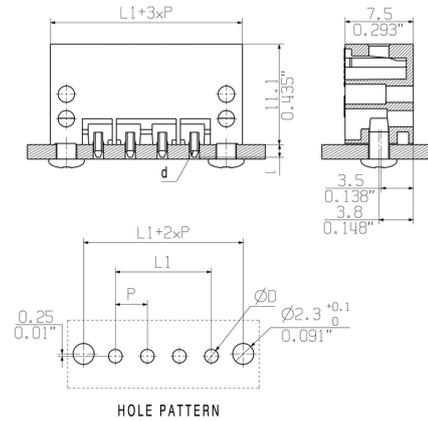
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Dimensional drawing



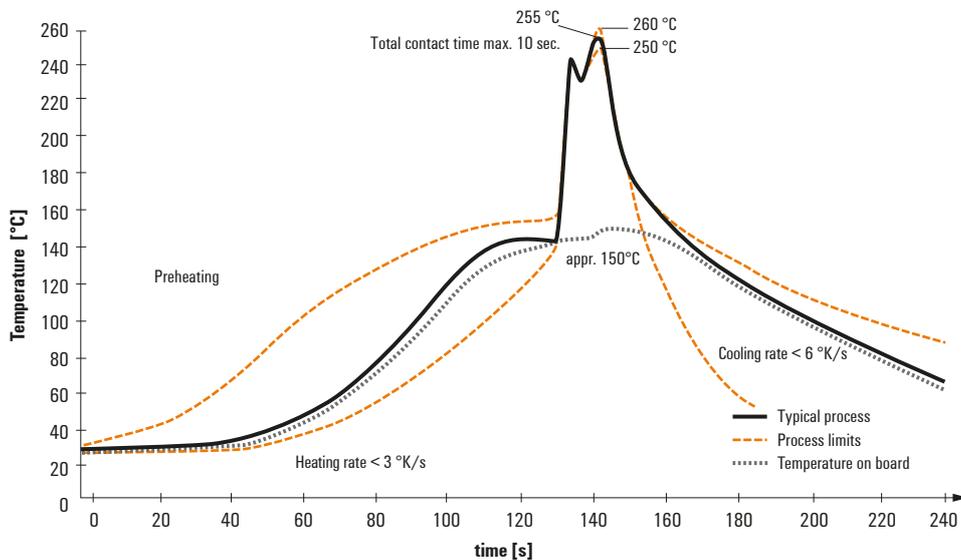
Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

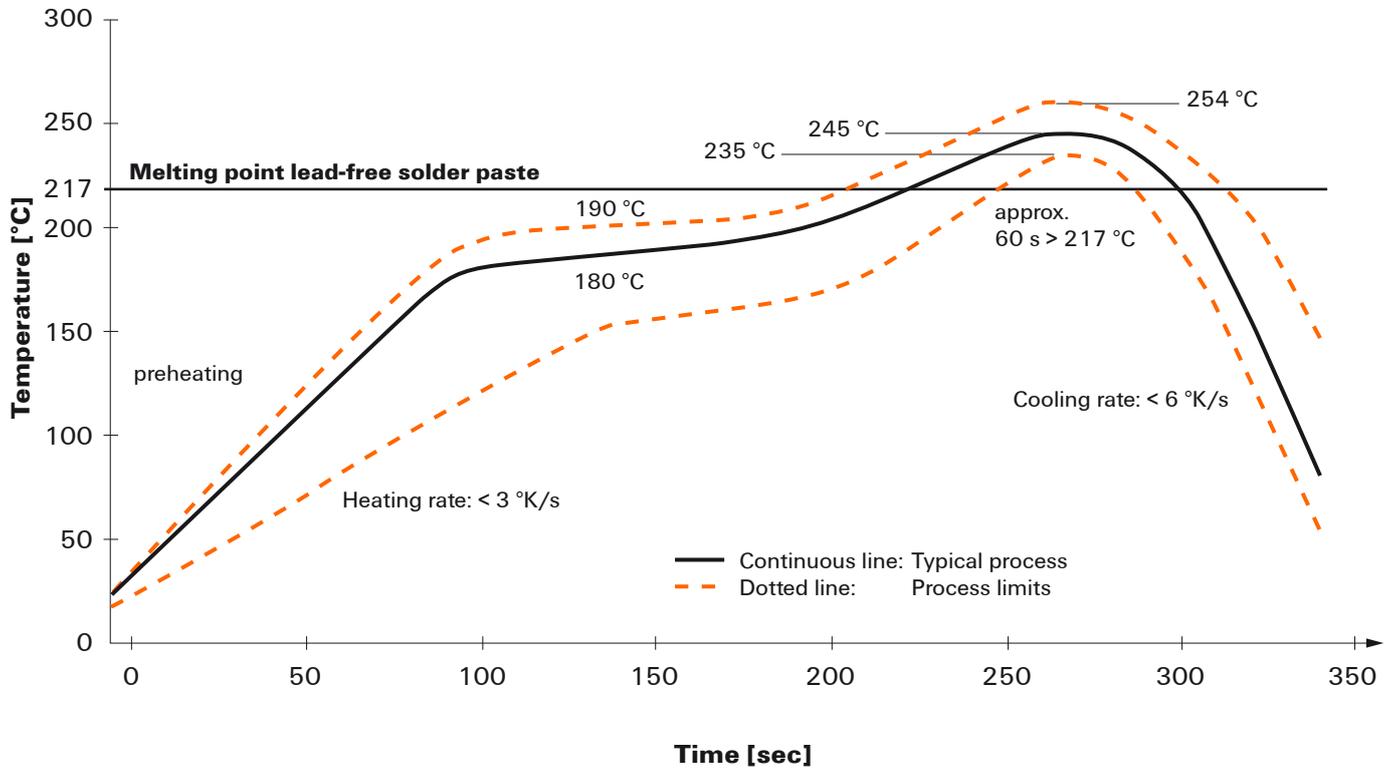
When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is ‚activated‘. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.